

Specification Sheet

Platinum Coated Silicon Wafer

(P-type/Boron doped with thermally grown SiO₂ surface)

Stock No: NS6130-10-1179, CAS: 7440-21-3

Product	:	Platinum Coated Silicon Wafer
Stock No	:	NS6130-10-1179
CAS	:	7440-21-3
Diameter	:	4" (101.6mm)
Crystal Orientation	:	< 100 >
Deposit Layers:		
Titanium Dioxide (TiO ₂)	:	400Å ± 50Å (Polished side)
Silicon Dioxide (SiO ₂)	:	1micron (0.50 micron on both sides of wafer)
Platinum (Pt)	:	1500Å ± 100Å (Polished side)
Growth Method	:	CZ
Resistivity	:	15 Ω-cm (1-20)
Surface	:	Single Side Polished
Coating	:	Platinum
Water Configuration	:	p-type Si + SiO ₂ + TiO ₂ + Pt
Surface roughness	:	≤ 5 Å
Thickness of Platinum Layer	:	150-200nm
Grade	:	Prime
Thickness of Si wafer	:	< 500 μm
RRG	:	≤12 %
Oxygen Contents	:	12.5-16.5 ppma
Carbon Contents	:	≤1 ppma
Shape	:	Cicular
Main Inspect Verifier	:	Manager QC

Note: Product Specification are subject to amendment and may change over time

Intelligent Materials Pvt. Ltd.

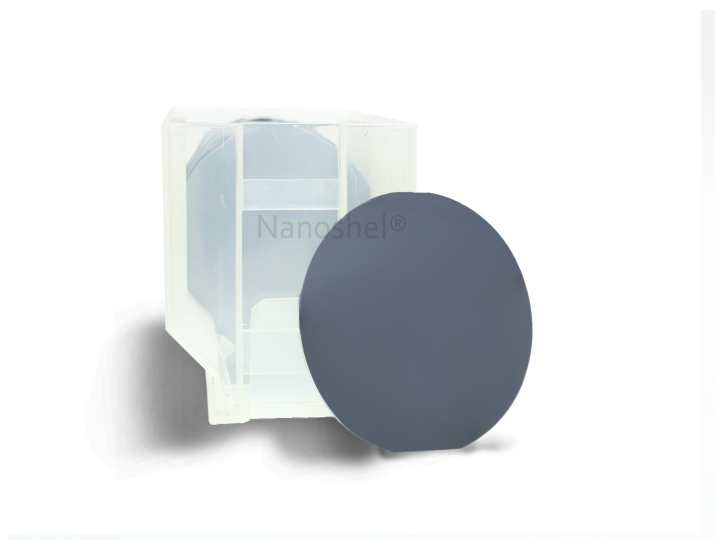
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Characterization of Platinum Coated Silicon Wafer



Platinum Coated Silicon Wafer



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